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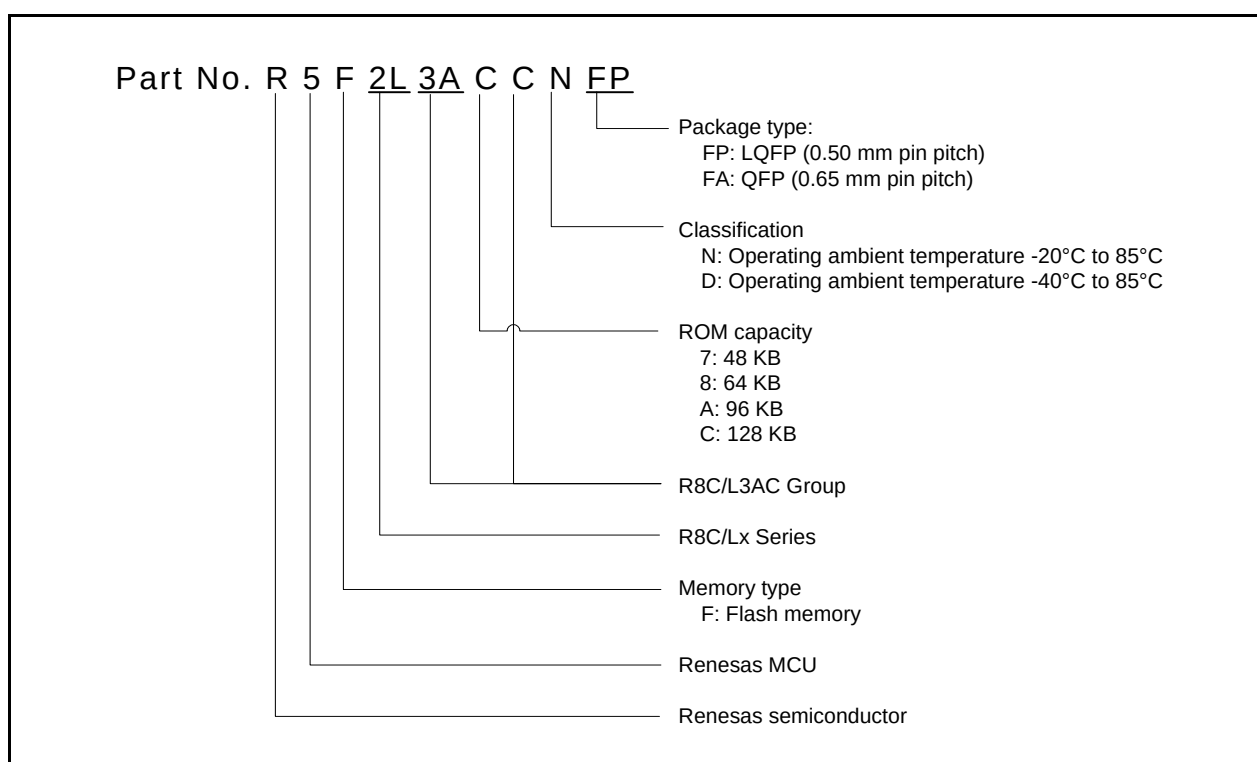
Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	LCD, POR, PWM, Voltage Detect, WDT
Number of I/O	52
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 10x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2l368cdfp-30

Table 1.10 Product List for R8C/L3AC Group**Current of Apr 2011**

Part No.	Internal ROM Capacity		Internal RAM Capacity	Package Type	Remarks
	Program ROM	Data Flash			
R5F2L3A7CNFP	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0100KB-A	N Version
R5F2L3A7CNFA	48 Kbytes	1 Kbyte × 4	6 Kbytes	PRQP0100JD-B	
R5F2L3A8CNFP	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0100KB-A	
R5F2L3A8CNFA	64 Kbytes	1 Kbyte × 4	8 Kbytes	PRQP0100JD-B	
R5F2L3AACNFP	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0100KB-A	
R5F2L3AACNFA	96 Kbytes	1 Kbyte × 4	10 Kbytes	PRQP0100JD-B	
R5F2L3ACCNFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0100KB-A	
R5F2L3ACCNFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PRQP0100JD-B	
R5F2L3A7CDFP	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0100KB-A	D Version
R5F2L3A7CDFA	48 Kbytes	1 Kbyte × 4	6 Kbytes	PRQP0100JD-B	
R5F2L3A8CDFP	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0100KB-A	
R5F2L3A8CDFA	64 Kbytes	1 Kbyte × 4	8 Kbytes	PRQP0100JD-B	
R5F2L3AACDFP	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0100KB-A	
R5F2L3AACDFA	96 Kbytes	1 Kbyte × 4	10 Kbytes	PRQP0100JD-B	
R5F2L3ACCDFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0100KB-A	
R5F2L3ACCDFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PRQP0100JD-B	

**Figure 1.4 Correspondence of Part No., with Memory Size and Package of R8C/L3AC Group**

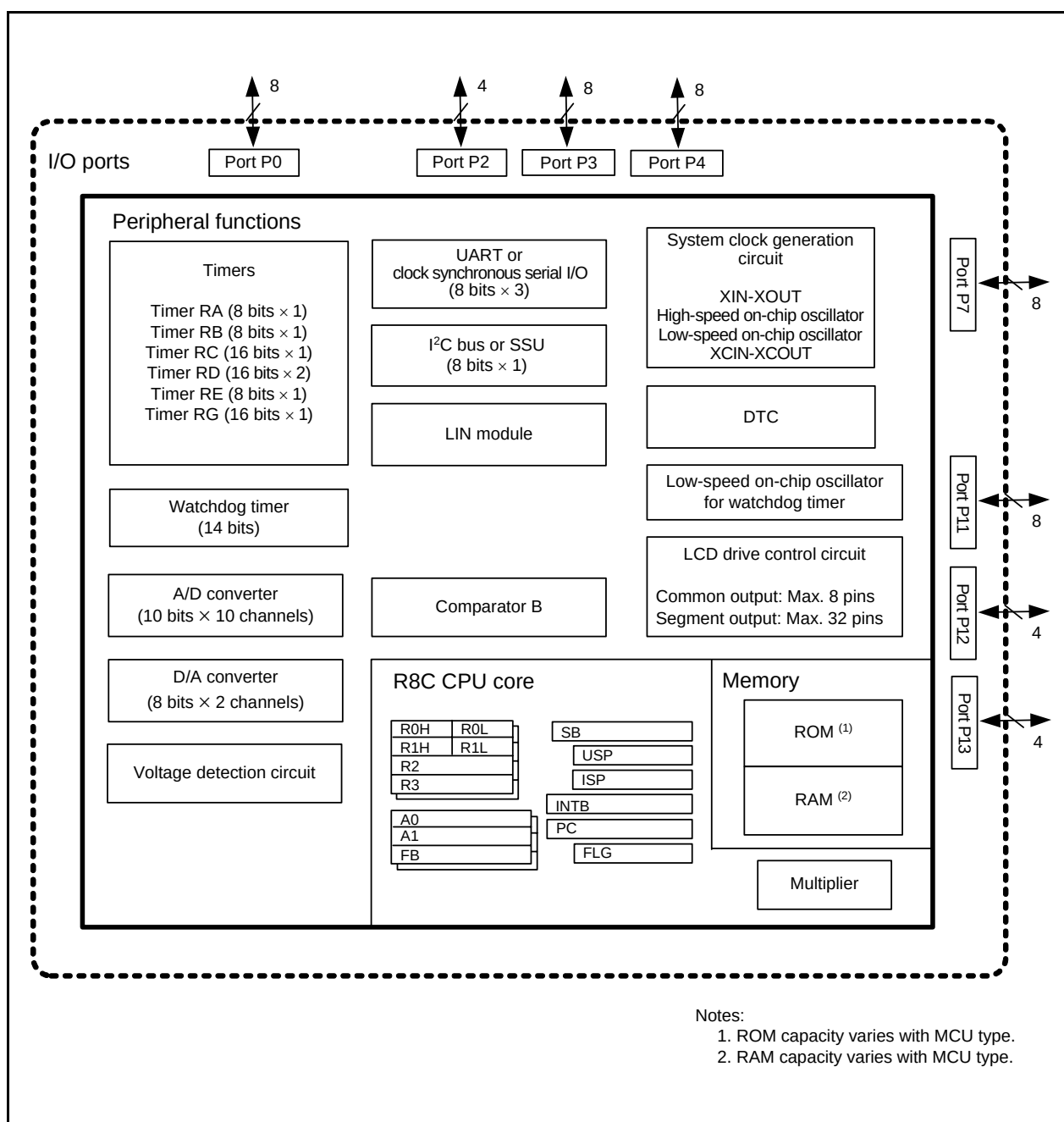


Figure 1.6 Block Diagram of R8C/L36C Group

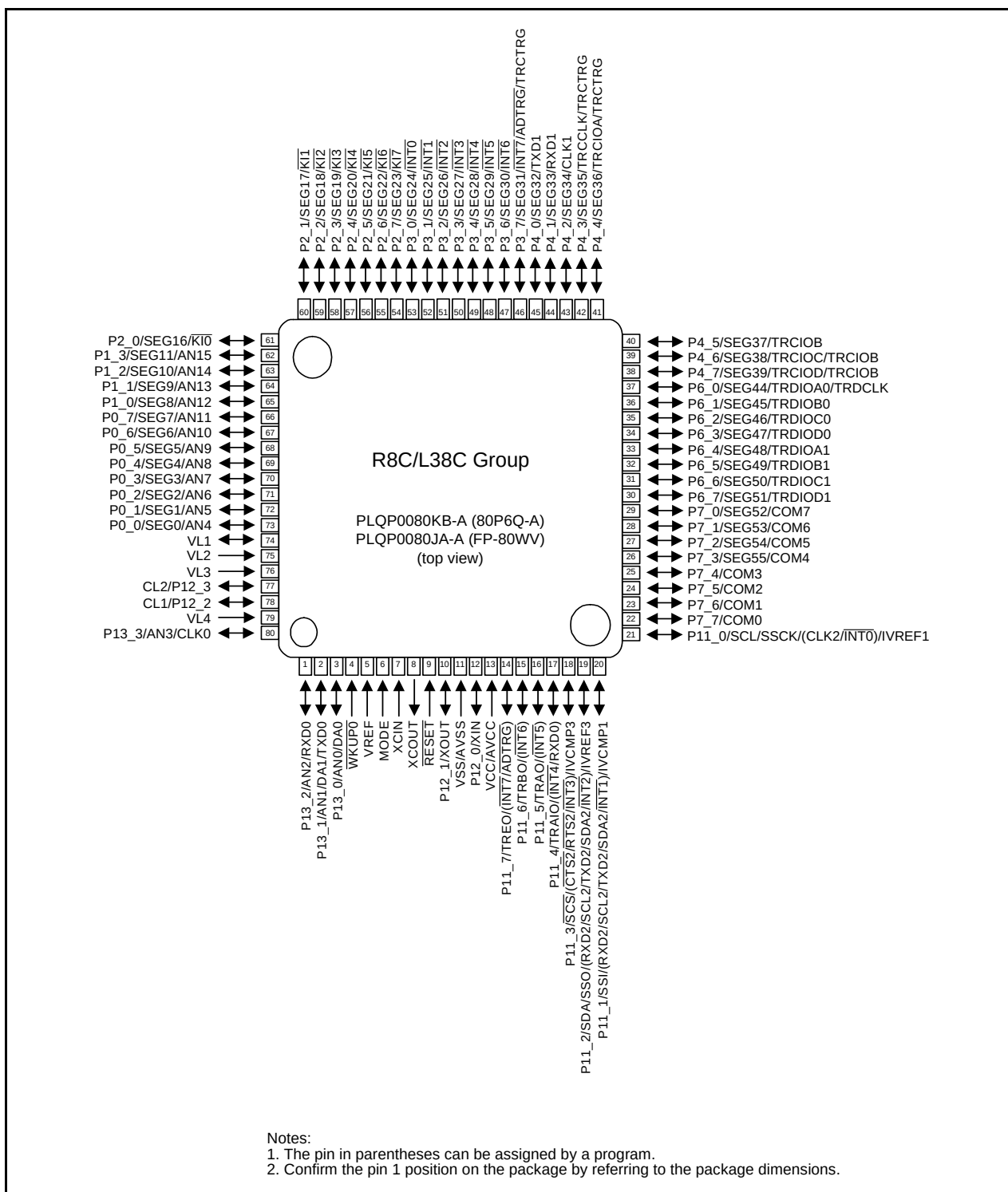


Figure 1.11 Pin Assignment (Top View) of PLQP0080KB-A and PLQP0080JA-A Packages

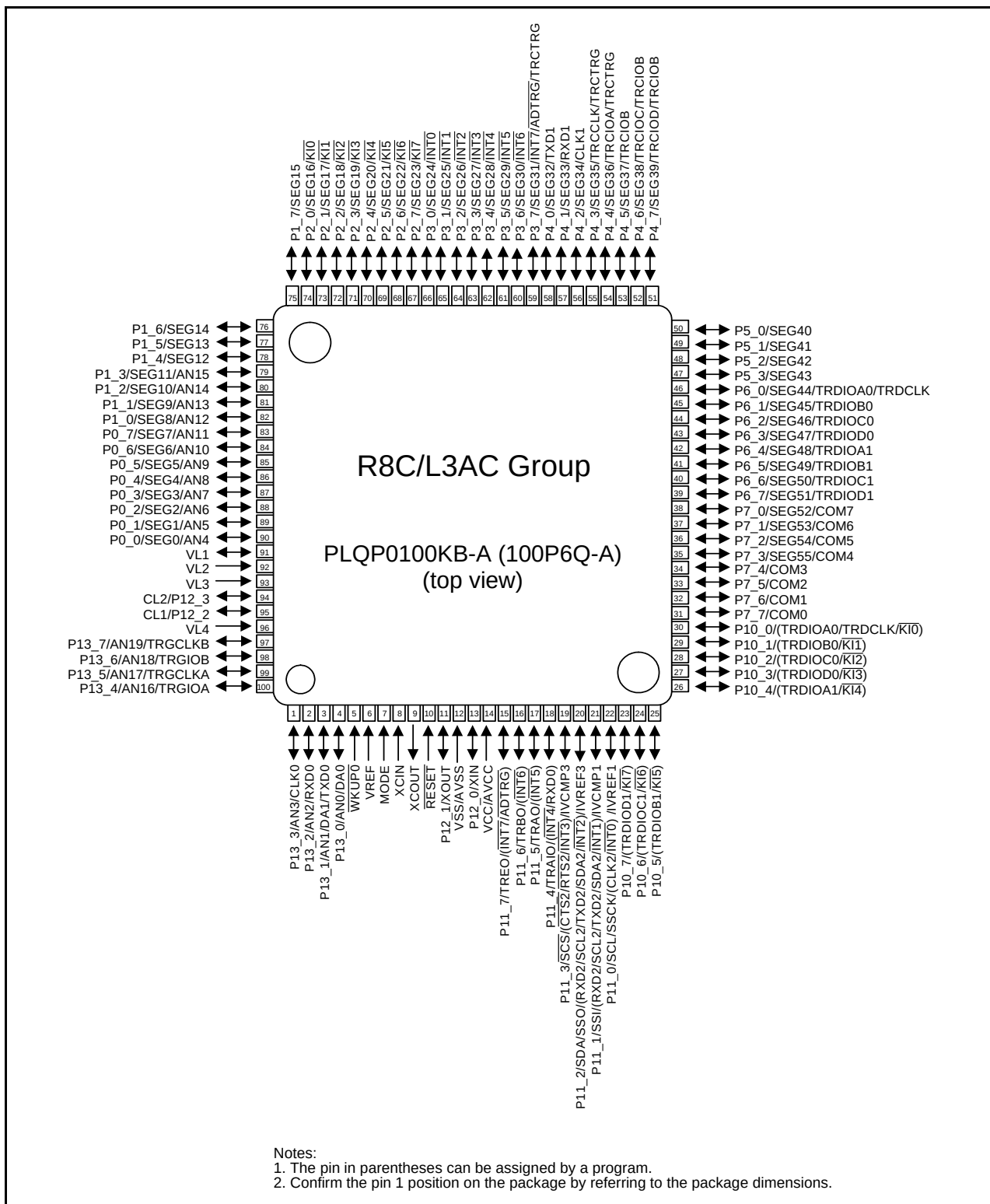


Figure 1.12 Pin Assignment (Top View) of PLQP0100KB-A Package

1.5 Pin Functions

Tables 1.14 and 1.15 list Pin Functions for R8C/L3AC Group.

Table 1.14 Pin Functions for R8C/L3AC Group (1)

Item	Pin Name	I/O Type	Description
Power supply input	VCC, VSS	–	Apply 1.8 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	–	Power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset input	$\overline{\text{RESET}}$	I	Driving this pin low resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
Power-off mode exit input	$\overline{\text{WKUP0}}$	I	This pin is provided for input to exit the mode used in power-off mode. Connect to VSS when not using power-off mode.
XIN clock input	XIN	I	These pins are provided for XIN clock generation circuit I/O. Connect a ceramic oscillator or a crystal oscillator between pins XIN and XOUT. ⁽¹⁾ To use an external clock, input it to the XIN pin and leave the XOUT pin open.
XIN clock output	XOUT	O	
XCIN clock input	XCIN	I	These pins are provided for XCIN clock generation circuit I/O. Connect a crystal oscillator between pins XCIN and XCOU. ⁽¹⁾ To use an external clock, input it to the XCIN pin and leave the XCOU pin open.
XCIN clock output	XCOU	O	
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT0}}$ to $\overline{\text{INT7}}$	I	$\overline{\text{INT}}$ interrupt input pins.
Key input interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI7}}$	I	Key input interrupt input pins
Timer RA	TRAIO	I/O	Timer RA I/O pin
	TRA0	O	Timer RA output pin
Timer RB	TRBO	O	Timer RB output pin
Timer RC	TRCLK	I	External clock input pin
	TRCTRG	I	External trigger input pin
	TRCIOA, TRCIOB, TRCIO, TRCIOD	I/O	Timer RC I/O pins
Timer RD	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDIOC0, TRDIOC1, TRDIOD0, TRDIOD1	I/O	Timer RD I/O pins
	TRDCLK	I	External clock input pin
Timer RE	TREO	O	Divided clock output pin
Timer RG	TRGCLKA, TRGCLKB	I	Timer RG input pins
	TRGIOA, TRGIOB	I/O	Timer RG I/O pins
Serial interface	CLK0, CLK1, CLK2	I/O	Transfer clock I/O pins
	RXD0, RXD1, RXD2	I	Serial data input pins
	TXD0, TXD1, TXD2	O	Serial data output pins
	$\overline{\text{CTS2}}$	I	Transmission control input pin
	$\overline{\text{RTS2}}$	O	Reception control output pin
	SCL2	I/O	I ² C mode clock I/O pin
	SDA2	I/O	I ² C mode data I/O pin

I: Input O: Output I/O: Input and output

Note:

1. Contact the oscillator manufacturer for oscillation characteristics.

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two sets of register banks.

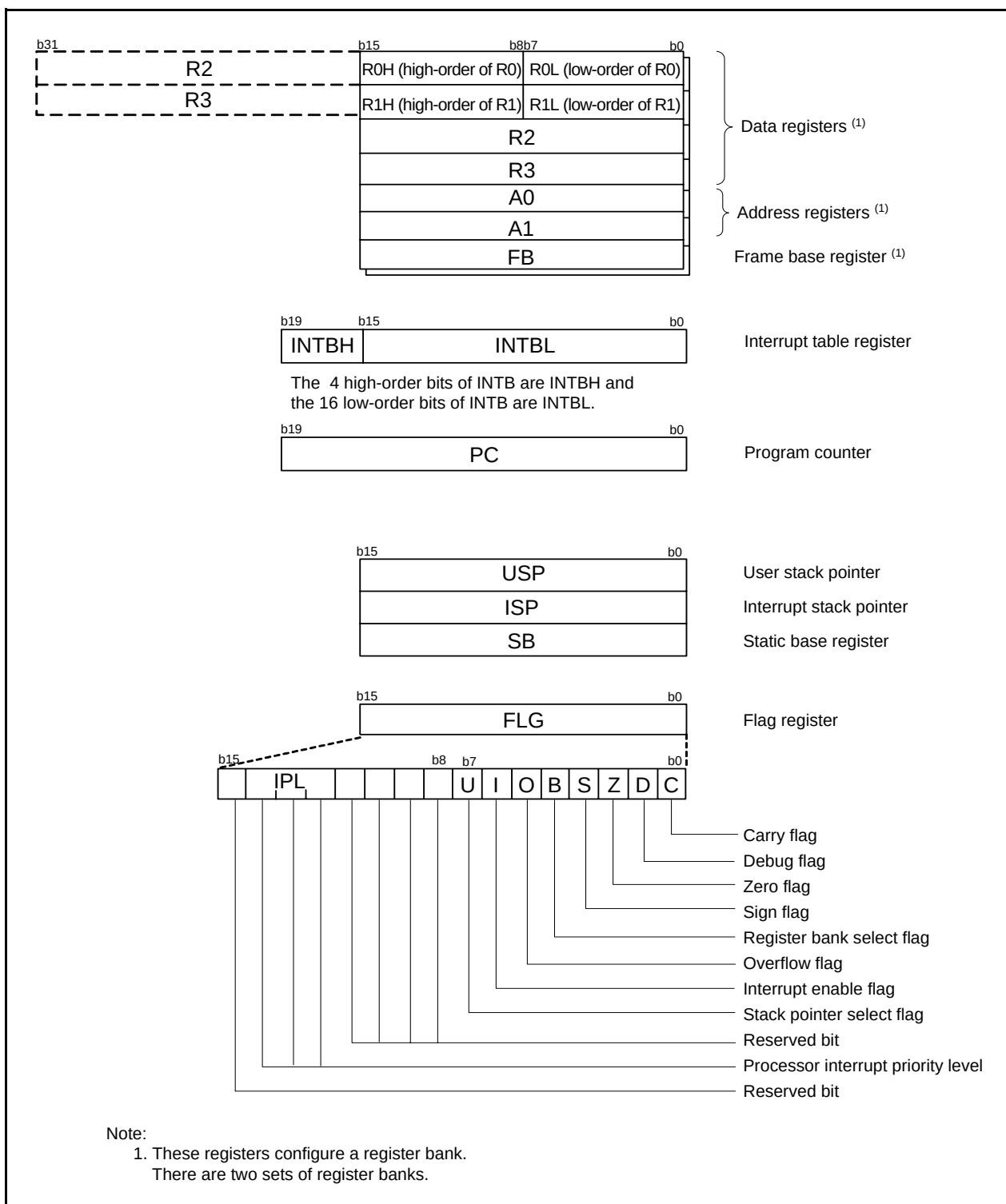


Figure 2.1 CPU Registers

2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3. R0 can be split into high-order bits (R0H) and low-order bits (R0L) to be used separately as 8-bit data registers. R1H and R1L are analogous to R0H and R0L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 is analogous to A0. A1 can be combined with A0 and as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the starting address of an interrupt vector table.

2.5 Program Counter (PC)

PC is 20 bits wide and indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP and ISP, are each 16 bits wide. The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated by the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0; otherwise to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value; otherwise to 0.

2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is set to 1.

2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow; otherwise to 0.

4. Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 4.1 to 4.16 list SFR Informations and Table 4.17 lists the ID Code Areas and Option Function Select Area. The description offered in this chapter is based on the R8C/L3AC Group.

Table 4.1 SFR Information (1) (1)

Address	Register	Symbol	After Reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	00100000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h	Module Standby Control Register	MSTCR	00h
0009h	System Clock Control Register 3	CM3	00h
000Ah	Protect Register	PRCR	00h
000Bh	Reset Source Determination Register	RSTFR	XXh (2)
000Ch	Oscillation Stop Detection Register	OCD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDTC	00111111b
0010h			
0011h			
0012h			
0013h			
0014h			
0015h	High-Speed On-Chip Oscillator Control Register 7	FRA7	When shipping
0016h			
0017h			
0018h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h 10000000b (3)
001Dh			
001Eh			
001Fh			
0020h	Power-Off Mode Control Register 0	POMCR0	X0000000b
0021h			
0022h			
0023h	High-Speed On-Chip Oscillator Control Register 0	FRA0	00h
0024h	High-Speed On-Chip Oscillator Control Register 1	FRA1	When shipping
0025h	High-Speed On-Chip Oscillator Control Register 2	FRA2	00h
0026h	On-Chip Reference Voltage Control Register	OCVREFCR	00h
0027h			
0028h			
0029h	High-Speed On-Chip Oscillator Control Register 4	FRA4	When Shipping
002Ah	High-Speed On-Chip Oscillator Control Register 5	FRA5	When Shipping
002Bh	High-Speed On-Chip Oscillator Control Register 6	FRA6	When Shipping
002Ch			
002Dh			
002Eh			
002Fh	High-Speed On-Chip Oscillator Control Register 3	FRA3	When shipping
0030h	Voltage Monitor Circuit Control Register	CMPA	00h
0031h	Voltage Monitor Circuit Edge Select Register	VCAC	00h
0032h			
0033h	Voltage Detect Register 1	VCA1	00001000b
0034h	Voltage Detect Register 2	VCA2	00h (4) 00100000b (5)
0035h			
0036h	Voltage Detection 1 Level Select Register	VD1LS	00000111b
0037h			
0038h	Voltage Monitor 0 Circuit Control Register	VW0C	1100X010b (4) 1100X011b (5)
0039h	Voltage Monitor 1 Circuit Control Register	VW1C	10001010b

X: Undefined

Notes:

- Blank spaces are reserved. No access is allowed.
- The CWR bit in the RSTFR register is set to 0 after power-on, voltage monitor 0 reset, or exit from power-off mode. Hardware reset, software reset, or watchdog timer reset does not affect this bit.
- The CSPROINI bit in the OFS register is set to 0.
- The LVDAS bit in the OFS register is set to 1.
- The LVDAS bit in the OFS register is set to 0.

Table 4.2 SFR Information (2) (1)

Address	Register	Symbol	After Reset
003Ah	Voltage Monitor 2 Circuit Control Register	VW2C	10000010b
003Bh			
003Ch			
003Dh			
003Eh			
003Fh			
0040h			
0041h	Flash Memory Ready Interrupt Control Register	FMRDYIC	XXXXX000b
0042h			
0043h	INT7 Interrupt Control Register	INT7IC	XX00X000b
0044h	INT6 Interrupt Control Register	INT6IC	XX00X000b
0045h	INT5 Interrupt Control Register	INT5IC	XX00X000b
0046h	INT4 Interrupt Control Register	INT4IC	XX00X000b
0047h	Timer RC Interrupt Control Register	TRCIC	XXXXX000b
0048h	Timer RD0 Interrupt Control Register	TRD0IC	XXXXX000b
0049h	Timer RD1 Interrupt Control Register	TRD1IC	XXXXX000b
004Ah	Timer RE Interrupt Control Register	TREIC	XXXXX000b
004Bh	UART2 Transmit Interrupt Control Register	S2TIC	XXXXX000b
004Ch	UART2 Receive Interrupt Control Register	S2RIC	XXXXX000b
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh	SSU Interrupt Control Register / IIC bus Interrupt Control Register (2)	SSUIC/IICIC	XXXXX000b
0050h			
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h	UART1 Transmit Interrupt Control Register	S1TIC	XXXXX000b
0054h	UART1 Receive Interrupt Control Register	S1RIC	XXXXX000b
0055h	INT2 Interrupt Control Register	INT2IC	XX00X000b
0056h	Timer RA Interrupt Control Register	TRAIC	XXXXX000b
0057h			
0058h	Timer RB Interrupt Control Register	TRBIC	XXXXX000b
0059h	INT1 Interrupt Control Register	INT1IC	XX00X000b
005Ah	INT3 Interrupt Control Register	INT3IC	XX00X000b
005Bh			
005Ch			
005Dh	INT0 Interrupt Control Register	INT0IC	XX00X000b
005Eh	UART2 Bus Collision Detection Interrupt Control Register	U2BCNIC	XXXXX000b
005Fh			
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h			
006Ah			
006Bh	Timer RG Interrupt Control Register	TRGIC	XXXXX000b
006Ch			
006Dh			
006Eh			
006Fh			
0070h			
0071h			
0072h	Voltage monitor 1 Interrupt Control Register	VCMP1IC	XXXXX000b
0073h	Voltage monitor 2 Interrupt Control Register	VCMP2IC	XXXXX000b
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
007Eh			
007Fh			

X: Undefined

Notes:

- Blank spaces are reserved. No access is allowed.
- Selectable by the IICSEL bit in the SSUICSR register.

Table 4.11 SFR Information (11) ⁽¹⁾

Address	Register	Symbol	After Reset
0280h	LCD Display Control Data Register	LRA16H	XXh
0281h		LRA17H	XXh
0282h		LRA18H	XXh
0283h		LRA19H	XXh
0284h		LRA20H	XXh
0285h		LRA21H	XXh
0286h		LRA22H	XXh
0287h		LRA23H	XXh
0288h		LRA24H	XXh
0289h		LRA25H	XXh
028Ah		LRA26H	XXh
028Bh		LRA27H	XXh
028Ch		LRA28H	XXh
028Dh		LRA29H	XXh
028Eh		LRA30H	XXh
028Fh		LRA31H	XXh
0290h		LRA32H	XXh
0291h		LRA33H	XXh
0292h		LRA34H	XXh
0293h		LRA35H	XXh
0294h		LRA36H	XXh
0295h		LRA37H	XXh
0296h		LRA38H	XXh
0297h		LRA39H	XXh
0298h		LRA40H	XXh
0299h		LRA41H	XXh
029Ah		LRA42H	XXh
029Bh		LRA43H	XXh
029Ch		LRA44H	XXh
029Dh		LRA45H	XXh
029Eh		LRA46H	XXh
029Fh		LRA47H	XXh
02A0h		LRA48H	XXh
02A1h		LRA49H	XXh
02A2h		LRA50H	XXh
02A3h		LRA51H	XXh
02A4h		LRA52H	XXh
02A5h		LRA53H	XXh
02A6h		LRA54H	XXh
02A7h		LRA55H	XXh
02A8h			
02A9h			
02AAh			
02ABh			
02ACh			
02ADh			
02AEh			
02AFh			
02B0h			
02B1h			
02B2h			
02B3h			
02B4h			
02B5h			
02B6h			
02B7h			
02B8h			
02B9h			
02BAh			
02BBh			
02BCh			
02BDh			
02BEh			
02BFh			

X: Undefined

Note:

- Blank spaces are reserved. No access is allowed.

5.2 Recommended Operating Conditions

Table 5.2 Recommended Operating Conditions
(VCC = 1.8 to 5.5 V and T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter			Conditions	Standard			Unit	
					Min.	Typ.	Max.		
V _{CC} /AV _{CC}	Supply voltage				1.8	—	5.5	V	
V _{SS} /AV _{SS}	Supply voltage				—	0	—	V	
V _{IH}	Input “H” voltage	Other than CMOS input			4.0 V ≤ V _{CC} ≤ 5.5 V	0.8 V _{CC}	—	V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0.8 V _{CC}	—	V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0.9 V _{CC}	—	V _{CC}	V
		CMOS input	Input level switching function (I/O port)	Input level selection : 0.35 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0.5 V _{CC}	—	V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0.55 V _{CC}	—	V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0.65 V _{CC}	—	V _{CC}	V
				Input level selection : 0.5 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0.65 V _{CC}	—	V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0.7 V _{CC}	—	V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0.8 V _{CC}	—	V _{CC}	V
				Input level selection : 0.7 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0.85 V _{CC}	—	V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0.85 V _{CC}	—	V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0.85 V _{CC}	—	V _{CC}	V
V _{IL}	Input “L” voltage	Other than CMOS input			4.0 V ≤ V _{CC} ≤ 5.5 V	0	—	0.2 V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0	—	0.2 V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0	—	0.05 V _{CC}	V
		CMOS input	Input level switching function (I/O port)	Input level selection : 0.35 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0	—	0.2 V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0	—	0.2 V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0	—	0.2 V _{CC}	V
				Input level selection : 0.5 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0	—	0.4 V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0	—	0.3 V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0	—	0.2 V _{CC}	V
				Input level selection : 0.7 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0	—	0.55 V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0	—	0.45 V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0	—	0.35 V _{CC}	V
I _{OH} (sum)	Peak sum output “H” current	Sum of all pins I _{OH} (peak)				—	—	–160	mA
I _{OH} (sum)	Average sum output “H” current	Sum of all pins I _{OH} (avg)				—	—	–80	mA
I _{OH} (peak)	Peak output “H” current	Port P10, P11 (2)				—	—	–40	mA
		Other pins				—	—	–10	mA
I _{OH} (avg)	Average output “H” current (1)	Port P10, P11 (2)				—	—	–20	mA
		Other pins				—	—	–5	mA
I _{OL} (sum)	Peak sum output “L” current	Sum of all pins I _{OL} (peak)				—	—	160	mA
I _{OL} (sum)	Average sum output “L” current	Sum of all pins I _{OL} (avg)				—	—	80	mA
I _{OL} (peak)	Peak output “L” current	Port P10, P11 (2)				—	—	40	mA
		Other pins				—	—	10	mA
I _{OL} (avg)	Average output “L” current (1)	Port P10, P11 (2)				—	—	20	mA
		Other pins				—	—	5	mA
f(XIN)	XIN clock input oscillation frequency			2.7 V ≤ V _{CC} ≤ 5.5 V	—	—	20	MHz	
				1.8 V ≤ V _{CC} < 2.7 V	—	—	5	MHz	
f(XCIN)	XCIN clock input oscillation frequency			1.8 V ≤ V _{CC} ≤ 5.5 V	—	32.768	50	kHz	
fOCO40M	When used as the count source for timer RC, timer RD, or timer RG (3)			2.7 V ≤ V _{CC} ≤ 5.5 V	32	—	40	MHz	
fOCO-F	fOCO-F frequency			2.7 V ≤ V _{CC} ≤ 5.5 V	—	—	20	MHz	
				1.8 V ≤ V _{CC} < 2.7 V	—	—	5	MHz	
—	System clock frequency			2.7 V ≤ V _{CC} ≤ 5.5 V	—	—	20	MHz	
				1.8 V ≤ V _{CC} < 2.7 V	—	—	5	MHz	
f(BCLK)	CPU clock frequency			2.7 V ≤ V _{CC} ≤ 5.5 V	—	—	20	MHz	
				1.8 V ≤ V _{CC} < 2.7 V	—	—	5	MHz	

Notes:

1. The average output current indicates the average value of current measured during 100 ms.
2. This applies when the drive capacity of the output transistor is set to High by registers P10DRR and P11DRR. When the drive capacity is set to Low, the value of any other pin applies.
3. f_{OCO40M} can be used as the count source for timer RC, timer RD, or timer RG in the range of V_{CC} = 2.7 V to 5.5V.

Table 5.6 Flash Memory (Program ROM) Characteristics
(V_{CC} = 2.7 to 5.5 V and T_{opr} = 0 to 60°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance ⁽¹⁾		1,000 ⁽²⁾	—	—	times
—	Byte program time		—	80	500	μs
—	Block erase time		—	0.3	—	s
t _d (SR-SUS)	Time delay from suspend request until suspend		—	—	5 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	ms
—	Time from suspend until erase restart		—	—	30+CPU clock × 1 cycle	μs
t _d (CMDRST-READY)	Time from when command is forcibly terminated until reading is enabled		—	—	30+CPU clock × 1 cycle	μs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		0	—	60	°C
—	Data hold time ⁽⁶⁾	Ambient temperature = 55°C	20	—	—	year

Notes:

1. Definition of programming/erasure endurance
The programming and erasure endurance is defined on a per-block basis.
If the programming and erasure endurance is n (n = 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.8 Voltage Detection 0 Circuit Characteristics
(V_{CC} = 1.8 to 5.5 V and T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V _{det0}	Voltage detection level V _{det0_0} ⁽¹⁾		1.80	1.90	2.05	V
	Voltage detection level V _{det0_1} ⁽¹⁾		2.15	2.35	2.50	V
	Voltage detection level V _{det0_2} ⁽¹⁾		2.70	2.85	3.05	V
	Voltage detection level V _{det0_3} ⁽¹⁾		3.55	3.80	4.05	V
—	Voltage detection 0 circuit response time ⁽³⁾	At the falling of V _{CC} from 5 V to (V _{det0_0} – 0.1) V	—	6	150	μs
—	Voltage detection circuit self power consumption	VCA25 = 1, V _{CC} = 5.0 V	—	1.5	—	μA
t _{d(E-A)}	Waiting time until voltage detection circuit operation starts ⁽²⁾		—	—	100	μs

Notes:

1. Select the voltage detection level with bits VDSEL0 and VDSEL1 in the OFS register.
2. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA25 bit in the VCA2 register to 0.
3. Time until the voltage monitor 0 reset is generated after the voltage passes V_{det0}.

Table 5.9 Voltage Detection 1 Circuit Characteristics
(V_{CC} = 1.8 to 5.5 V and T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V _{det1}	Voltage detection level V _{det1_0} ⁽¹⁾	At the falling of V _{CC}	2.00	2.20	2.40	V
	Voltage detection level V _{det1_1} ⁽¹⁾	At the falling of V _{CC}	2.15	2.35	2.55	V
	Voltage detection level V _{det1_2} ⁽¹⁾	At the falling of V _{CC}	2.30	2.50	2.70	V
	Voltage detection level V _{det1_3} ⁽¹⁾	At the falling of V _{CC}	2.45	2.65	2.85	V
	Voltage detection level V _{det1_4} ⁽¹⁾	At the falling of V _{CC}	2.60	2.80	3.00	V
	Voltage detection level V _{det1_5} ⁽¹⁾	At the falling of V _{CC}	2.75	2.95	3.15	V
	Voltage detection level V _{det1_6} ⁽¹⁾	At the falling of V _{CC}	2.85	3.10	3.40	V
	Voltage detection level V _{det1_7} ⁽¹⁾	At the falling of V _{CC}	3.00	3.25	3.55	V
	Voltage detection level V _{det1_8} ⁽¹⁾	At the falling of V _{CC}	3.15	3.40	3.70	V
	Voltage detection level V _{det1_9} ⁽¹⁾	At the falling of V _{CC}	3.30	3.55	3.85	V
	Voltage detection level V _{det1_A} ⁽¹⁾	At the falling of V _{CC}	3.45	3.70	4.00	V
	Voltage detection level V _{det1_B} ⁽¹⁾	At the falling of V _{CC}	3.60	3.85	4.15	V
	Voltage detection level V _{det1_C} ⁽¹⁾	At the falling of V _{CC}	3.75	4.00	4.30	V
	Voltage detection level V _{det1_D} ⁽¹⁾	At the falling of V _{CC}	3.90	4.15	4.45	V
	Voltage detection level V _{det1_E} ⁽¹⁾	At the falling of V _{CC}	4.05	4.30	4.60	V
	Voltage detection level V _{det1_F} ⁽¹⁾	At the falling of V _{CC}	4.20	4.45	4.75	V
—	Hysteresis width at the rising of V _{CC} in voltage detection 1 circuit	V _{det1_0} to V _{det1_5} selected	—	0.07	—	V
		V _{det1_6} to V _{det1_F} selected	—	0.10	—	V
—	Voltage detection 1 circuit response time ⁽²⁾	At the falling of V _{CC} from 5 V to (V _{det1_0} – 0.1) V	—	60	150	μs
—	Voltage detection circuit self power consumption	VCA26 = 1, V _{CC} = 5.0 V	—	1.7	—	μA
t _{d(E-A)}	Waiting time until voltage detection circuit operation starts ⁽³⁾		—	—	100	μs

Notes:

1. Select the voltage detection level with bits VD1S0 to VD1S3 in the VD1LS register.
2. Time until the voltage monitor 1 interrupt request is generated after the voltage passes V_{det1}.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

Table 5.15 LCD Drive Control Circuit Characteristics
(V_{CC} = 1.8 to 5.5 V, V_{SS} = 0 V, and T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
VLCD	LCD power supply voltage	VLCD = VL4	2.2	—	5.5	V
VL3	VL3 voltage		VL2	—	VL4	V
VL2	VL2 voltage	R8C/L35C	VL1	—	VL4	V
		R8C/L36C, R8C/L38C, R8C/L3AC	VL1	—	VL3	V
VL1	VL1 voltage		1	—	VL2 (3)	V
—	VL1 internally-generated voltage accuracy (1)		Setting voltage –0.2	Setting voltage	Setting voltage +0.2	V
f(FR)	Frame frequency		50	—	180	Hz
ILCD	LCD drive control circuit current		—	(Note 2)	—	μA

Notes:

1. The voltage is selected with bits LVLS0 to LVLS3 in the LCR1 register.
2. Refer to **Table 5.18 DC Characteristics (2)**, **Table 5.20 DC Characteristics (4)**, and **Table 5.22 DC Characteristics (6)**.
3. The VL1 voltage should be VCC or below.

Table 5.16 Power-Off Mode Characteristics
(V_{CC} = 2.2 to 5.5 V, V_{SS} = 0 V, and T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
—	Power-off mode operating supply voltage		2.2	—	5.5	V

Table 5.20 DC Characteristics (4) [2.7 V ≤ V_{CC} < 4.0 V]
(T_{OP} = −20 to 85°C (N version) / −40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Condition								Standard			Unit	
			Oscillation Circuit		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other		Min.	Typ. (3)	Max.		
XIN (2)	XCIN	High-Speed (fOCO-F)	Low-Speed												
I _{CC}	Power supply current (1)	High-speed clock mode	20 MHz	Off	Off	125 kHz	No division	—			—	7.0	14.5	mA	
			10 MHz	Off	Off	125 kHz	No division	—			—	3.6	10	mA	
			20 MHz	Off	Off	125 kHz	Divide-by-8	—			—	3.0	—	mA	
			10 MHz	Off	Off	125 kHz	Divide-by-8	—			—	1.5	—	mA	
		High-speed on-chip oscillator mode	Off	Off	20 MHz	125 kHz	No division	—			—	7.0	14.5	mA	
			Off	Off	20 MHz	125 kHz	Divide-by-8	—			—	3.0	—	mA	
			Off	Off	10 MHz	125 kHz	No division	—			—	4.0	—	mA	
			Off	Off	10 MHz	125 kHz	Divide-by-8	—			—	1.7	—	mA	
			Off	Off	4 MHz	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRD = 1 MSTTRC = 1 MSTTRG = 1			—	1	—	mA	
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 VCA20 = 0			—	85	390	μA	
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 VCA20 = 0			—	90	400	μA	
			Off	32 kHz	Off	Off	No division	FMSTP = 1 VCA20 = 0	Flash memory off Program operation on RAM			—	50	—	μA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1	While a WAIT instruction is executed Peripheral clock operation		—	15	90	μA	
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off		—	5	80	μA	
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 0	While a WAIT instruction is executed Peripheral clock off Timer RE operation in real-time clock mode	LCD drive control circuit (4) When external division resistors are used	—	5	—	μA	
									LCD drive control circuit (5) When the internal voltage multiplier is used			—	11	—	μA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off Timer RE operation in real-time clock mode		—	3.5	—	μA	
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	T _{OP} = 25°C Peripheral clock off		—	2	5.0	μA	
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	T _{OP} = 85°C Peripheral clock off		—	13.0	—	μA	
		Power-off mode	Off	Off	Off	Off	—	—		T _{OP} = 25°C		—	0.02	0.2	μA
			Off	Off	Off	Off	—	—		T _{OP} = 85°C		—	0.3	—	μA

Notes:

- V_{CC} = 2.7 V to 4.0 V, single chip mode, output pins are open, and other pins are V_{SS}.
- XIN is set to square wave input.
- V_{CC} = 3.0 V
- V_{LCD} = V_{CC}, external division resistors are used for VL4 to VL1, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG55 are selected, and segment and common output pins are open. The standard value does not include the current that flows through external division resistors.
- The internal voltage multiplier is used, bits LVLS3 to LVLS0 in the LCR1 register = 1011b, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG55 are selected, and segment and common output pins are open.

5.5 AC Characteristics

Table 5.23 Timing Requirements of Synchronous Serial Communication Unit (SSU)
($V_{CC} = 1.8$ to 5.5 V, $V_{SS} = 0$ V, and $T_{opr} = -20$ to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
tsucyc	SSCK clock cycle time			4	—	—	tcyc (1)
tHI	SSCK clock "H" width			0.4	—	0.6	tsucyc
tLO	SSCK clock "L" width			0.4	—	0.6	tsucyc
trISE	SSCK clock rising time	Master		—	—	1	tcyc (1)
		Slave		—	—	1	μs
tFALL	SSCK clock falling time	Master		—	—	1	tcyc (1)
		Slave		—	—	1	μs
tsu	SSO, SSI data input setup time			100	—	—	ns
tH	SSO, SSI data input hold time			1	—	—	tcyc (1)
tLEAD	$\overline{\text{SCS}}$ setup time	Slave		1tcyc + 50	—	—	ns
tLAG	$\overline{\text{SCS}}$ hold time	Slave		1tcyc + 50	—	—	ns
tOD	SSO, SSI data output delay time			—	—	1	tcyc (1)
tsA	SSI slave access time		$2.7\text{ V} \leq V_{CC} \leq 5.5\text{ V}$	—	—	$1.5\text{tcyc} + 100$	ns
			$1.8\text{ V} \leq V_{CC} < 2.7\text{ V}$	—	—	$1.5\text{tcyc} + 200$	ns
toR	SSI slave out open time		$2.7\text{ V} \leq V_{CC} \leq 5.5\text{ V}$	—	—	$1.5\text{tcyc} + 100$	ns
			$1.8\text{ V} \leq V_{CC} < 2.7\text{ V}$	—	—	$1.5\text{tcyc} + 200$	ns

Note:

1. $1\text{tcyc} = 1/f_1(\text{s})$

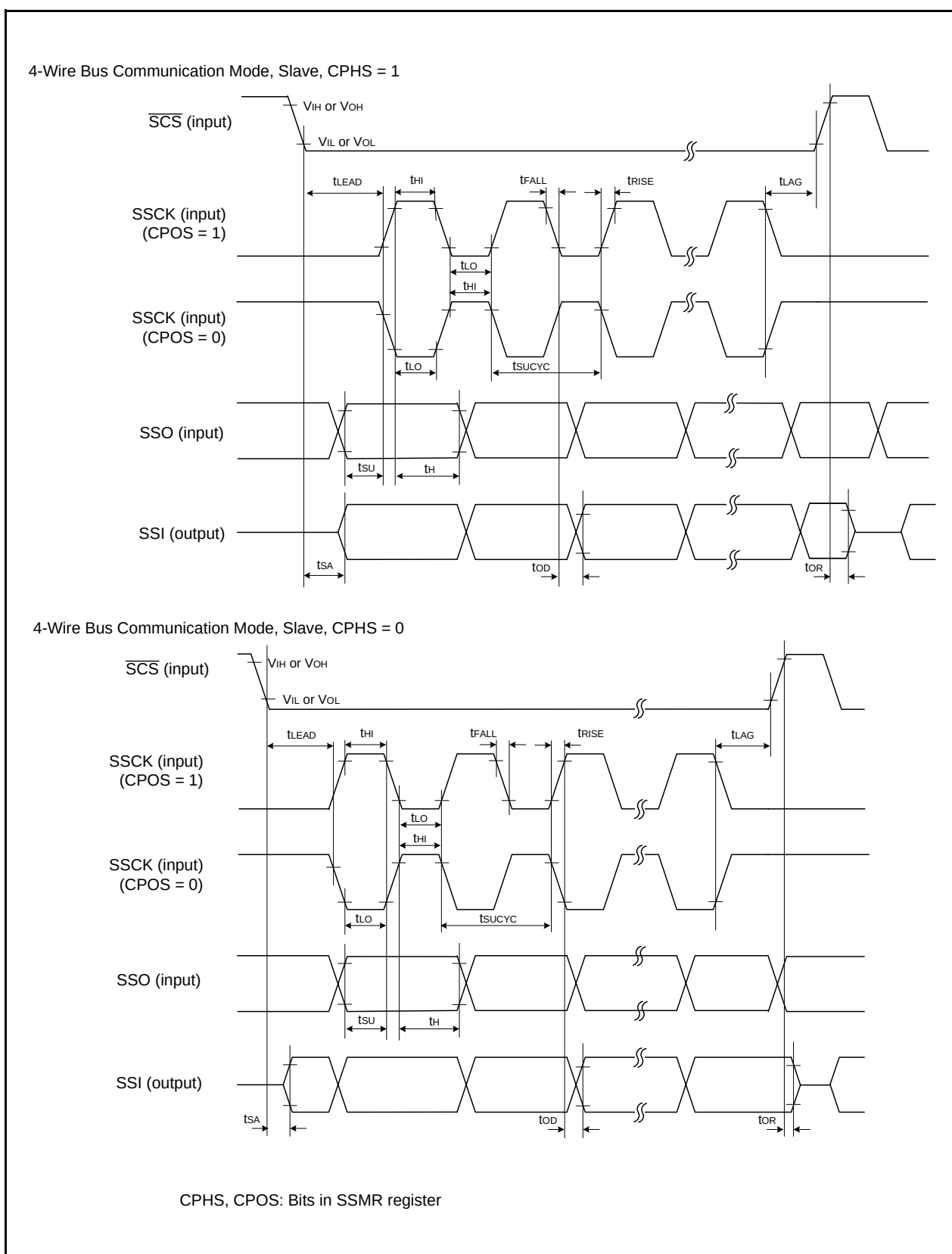


Figure 5.5 I/O Timing of Synchronous Serial Communication Unit (SSU) (Slave)

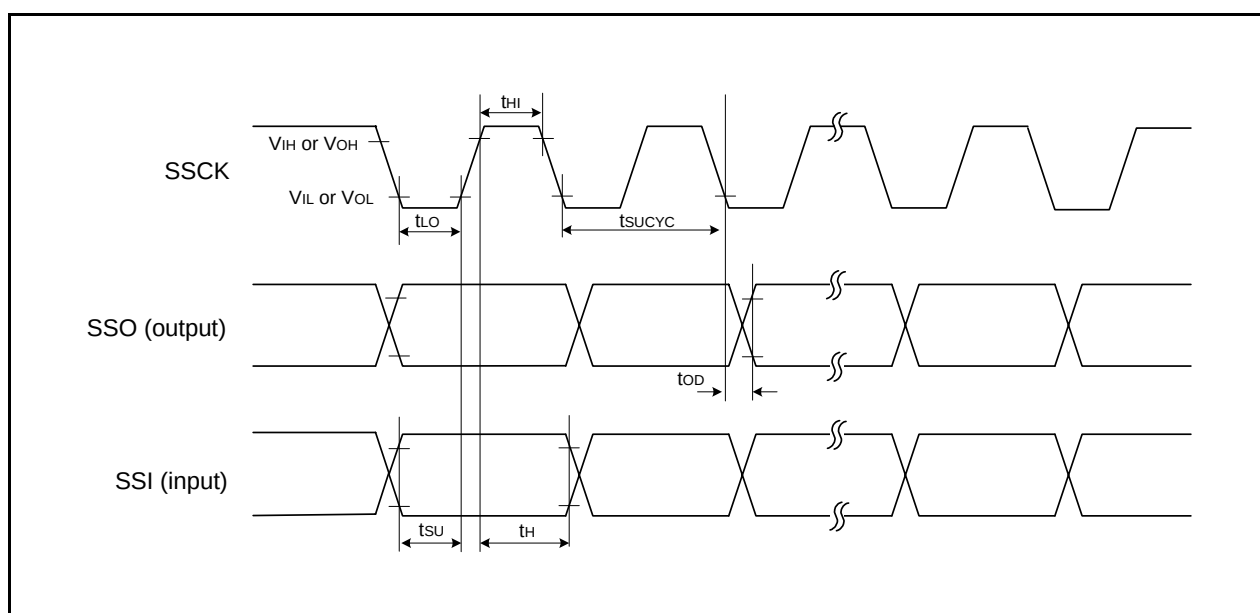
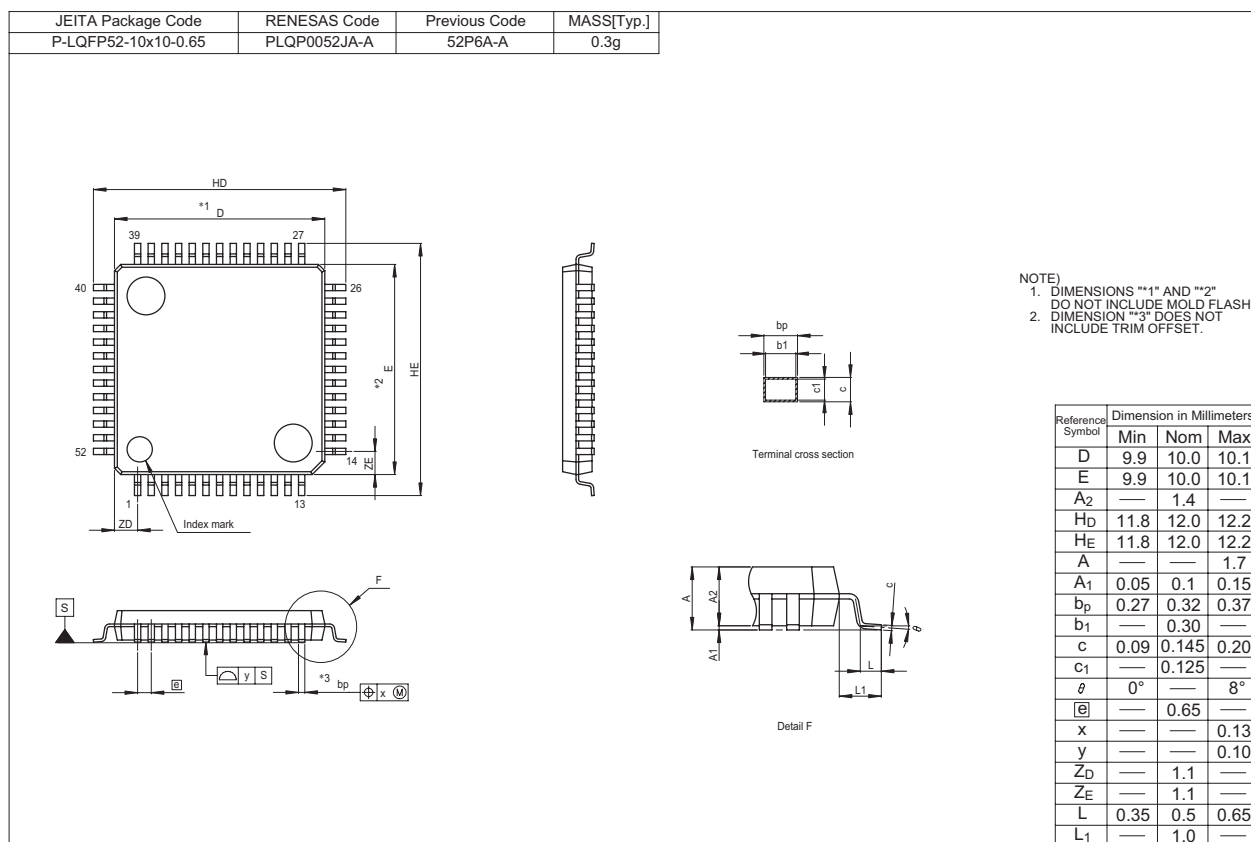


Figure 5.6 I/O Timing of Synchronous Serial Communication Unit (SSU) (Clock Synchronous Communication Mode)

Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Electronics web site.



General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

- The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

- The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

- The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.